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DEVICE, AND METHOD OF
MANUFACTURING WIRING SUBSTRATE****H01R 12/52** (2006.01)**H01R 4/70** (2006.01)(52) **U.S. Cl.****CPC .. H01L 23/49833** (2013.01); **H01L 23/49822**
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ABSTRACT

A wiring substrate has a first wiring substrate, plurality of second wiring substrates, and an adhesive layer. The plurality of second wiring substrates are arranged adjacent to each other on the first wiring substrate. The adhesive layer adheres the first wiring substrate and the plurality of second wiring substrates to each other. The adhesive layer has a filling portion that fills a groove portion formed by opposing of side surfaces of adjacent ones of the plurality of second wiring substrates.

